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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Po-Yao Lin et al.

Serial No. 09/379,599

Filed: August 24, 1999

For: Integrated Circuit Package with
Multiple Heat Dissipation Paths



Art Unit: 2835

Examiner: Chervinsky, B.

Atty Docket: 0694/00063

SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

Sir:

In accordance with the Notice of Allowability mailed September 27, 2000,
Applicants submit herewith 1 sheet of formal drawings of Figs. 1-3.

Respectfully submitted,



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Date: 11-07-00